

Thermal Gel / XK-G60

Introduction

Syringes packaging, automated production, high temperature, non-corrosive metal, 100% thermal curing putty. XK-G series is a high performance thermal gel, it base on silicone, filled with a variety of high-performance ceramic powder. It has high thermal conductivity, low thermal resistance, good insulation and infinite compression characteristics.

Features

Thermal conductivity 3.0~8.0W/m.K
 High compressibility
 Very low thermal resistance
 Good creep performance
 Best for north bridge IC

Applications

Consumer electronics
 Automotive Systems
 Telecommunications
 Hand-set applications



	Unit	XK-G60	Method
Color		Light Blue	Visual
Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	g/min	10-18	
Specific Gravity	g/cm ³	3.3	ASTM D792
Volume Resistivity	Ωcm	>10 ¹¹	ASTM D257
Thermal Conductivity	W/mK	6.5	ASTM D5470
Breakdown Voltage	KV/mm	>10	ASTM D149
Dielectric Constant	1	8.0	ASTM D150
Low Limit BLT Thickness	mm	0.15	ASTM D374
Application Temperature	°C	-50~150	
Shelf life	month	18	
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Coefficient of Thermal Expansion	ppm/K	200	
Flammability	UL94	V-0	UL94